

ABSTRACT OF THE DISCLOSURE

A bonded anisotropic conductive film fabricated using a plastic material and a plurality of conductive particles inside the plastic material. The plastic material is a thermal set material hardening after being raised to a first temperature. Each conductive particle inside the plastic material includes a conductive bead, a bonding layer and a flux layer. The bonding layer is formed over the conductive bead enclosing the conductive bead entirely. The flux layer is formed over the bonding layer. The bonding layer has a melting point at a second temperature where the second temperature is higher than the first temperature.

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